

AN-1859 LP38512MR-ADJ Evaluation Board

1 Introduction

This board is designed to allow the evaluation of the LP38512MR-ADJ Voltage Regulator. Each board is assembled and tested in the factory. This evaluation board has the PSOP-8 package mounted, and the output voltage is set to 1.20V.

2 General Description

The LP38512MR-ADJ is an adjustable LDO linear regulator capable of supplying up to 1.5A of output current, and incorporates an Enable function.

The device has been designed to work with 10 μ F input and output ceramic capacitors. Footprints areas for C_{IN} and C_{OUT} will allow for a variety of sizes.

3 Operation

The input voltage, applied between V_{IN} and GND, should be at least 2.25V, or at least 500 mV greater than V_{OUT} , whichever value is larger. The input voltage should be no greater than 5.5V, which is the high end of the Operating Rating voltage.

Loads can be connected to V_{OUT} with reference to GND.

V_{OUT} and V_{IN} test points are provided on the board to allow accurate measurements directly onto the input and output pins of the device, eliminating any voltage drop on the PCB traces or connecting wires to the load.

4 Setting V_{OUT}

The output voltage is set using the external resistive divider R1 and R2. The output voltage is given by the formula:

$$V_{OUT} = V_{ADJ} \times (1 + (R1 / R2)) \quad (1)$$

It is recommended that the values selected for R1 and R2 are such that the parallel value is less than 1.00 k Ω . This is to prevent internal parasitic capacitances on the ADJ pin from interfering with the F_z pole set by R1 and C_{FF} .

$$((R1 \times R2) / (R1 + R2)) \leq 1.00 \text{ k}\Omega \quad (2)$$

[Table 1](#) lists some suggested, best fit, standard $\pm 1\%$ resistor values for R1 and R2, and a standard $\pm 10\%$ capacitor values for C_{FF} , for a range of V_{OUT} values. Other values of R1, R2, and C_{FF} are available that will give similar results.

Refer to *AN-1378 Method for Calculating Output Voltage Tolerances in Adjustable Regulators Application Report* ([SNVA112](#)) for additional information on how resistor tolerances affect the calculated V_{OUT} value.

The LP38512MR-ADJ Evaluation board is assembled with a 1.40 k Ω $\pm 1\%$ resistor for R1, and a 1.00 k Ω $\pm 1\%$ resistor for R2. This sets V_{OUT} to 1.20V.

$$V_{OUT} = 500 \text{ mV} \times (1 + (1.40 \text{ k}\Omega / 1.00 \text{ k}\Omega)) \quad (3)$$

Table 1. Suggested Components

V_{OUT}	R1	R2	C_{FF}	F_z
0.80V	1.07 k Ω	1.78 k Ω	4700 pF	31.6 kHz
1.00V	1.00 k Ω	1.00 k Ω	4700 pF	33.8 kHz
1.20V	1.40 k Ω	1.00 k Ω	3300 pF	34.4 kHz
1.50V	2.00 k Ω	1.00 k Ω	2700 pF	29.5 kHz
1.80V	2.94 k Ω	1.13 k Ω	1500 pF	36.1 kHz
2.00V	1.02 k Ω	340 Ω	4700 pF	33.2 kHz
2.50V	1.02 k Ω	255 Ω	4700 pF	33.2 kHz
3.00V	1.00 k Ω	200 Ω	4700 pF	33.8 kHz
3.30V	2.00 k Ω	357 Ω	2700 pF	29.5 kHz

5 Selecting C_{FF}

A capacitor placed across the gain resistor R1 will provide additional phase margin to improve load transient response of the device. This capacitor, C_{FF} , in parallel with R1, will form a zero in the loop response given by the formula:

$$F_z = (1 / (2 \times \pi \times C_{FF} \times R1)) \quad (4)$$

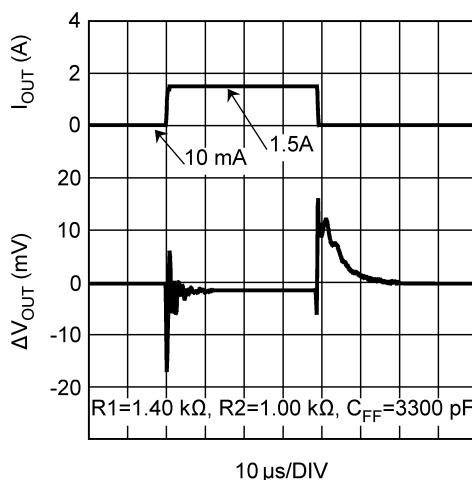
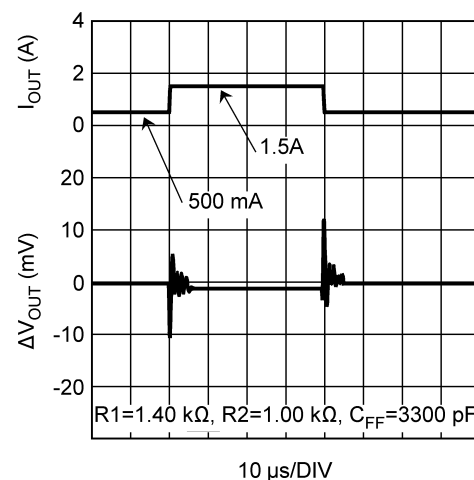
The value for C_{FF} should be selected to set a zero frequency (F_z) between 25 kHz and 50 kHz using the formula:

$$C_{FF} = 1 / (2 \times \pi \times F_z \times R1) \quad (5)$$

The closest standard 10% value is usually adequate for C_{FF} .

The LP38512MR-ADJ Evaluation board is assembled with a 3300 pF capacitor for C_{FF} . This sets F_z to approximately 34 kHz.

$$F_z = (1 / (2 \times \pi \times 3300 \text{ pF} \times 1.40 \text{ k}\Omega)) = 34.4 \text{ kHz} \quad (6)$$


Figure 1. 10 mA to 1.5A Load Transient Response

Figure 2. 500 mA to 1.5A Load Transient Response

6 Enable Function

ON/OFF control is provided by supplying a logic level signal to the Enable pin. A minimum V_{EN} value of 1.2V is typically required at this pin to enable the LDO output. The LDO output will be shutdown when the V_{EN} value is typically 0.6V or less. The V_{EN} threshold incorporates approximately 100 mV of hysteresis.

In applications where the LP38512MR-ADJ is operated continuously the Enable pin can be connected directly to V_{IN} . The Enable pin has no default bias and must not be left floating. The Enable pin must be actively driven to the appropriate voltage level.

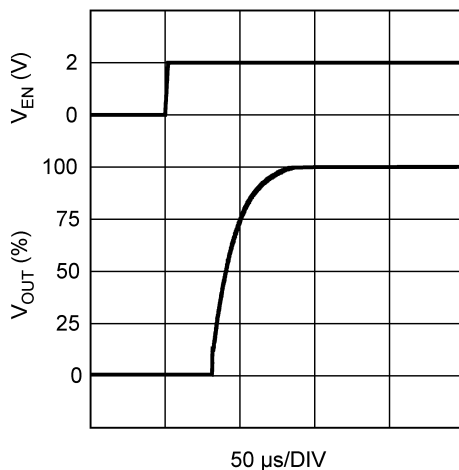


Figure 3. V_{OUT} vs V_{EN}

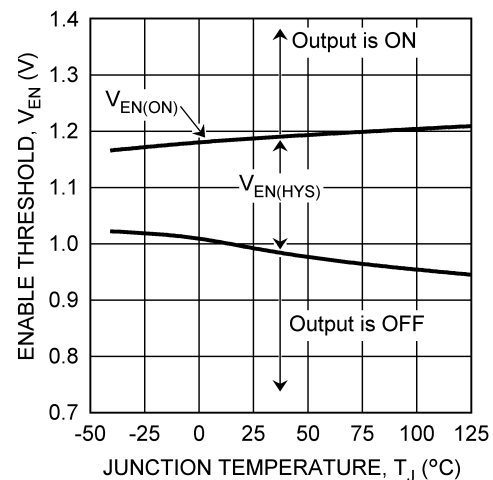


Figure 4. Enable Thresholds

7 Power Dissipation

The PSOP-8 package alone has a junction to ambient thermal resistance (θ_{JA}) rating of 168°C/W when mounted to the minimum land area (EIA/JESD51-3). When mounted on the LP38512MR-ADJ Evaluation Board the θ_{JA} rating is approximately 40°C/W.

The exposed DAP is soldered to the copper area immediately under the package. The top copper surface area is extended to additional copper area on the bottom of the board by five thermal vias placed inside the DAP land area.

With the 40°C/W thermal rating the LP38512MR-ADJ evaluation board will dissipate a maximum of 2.5W with $T_A = 25^\circ\text{C}$.

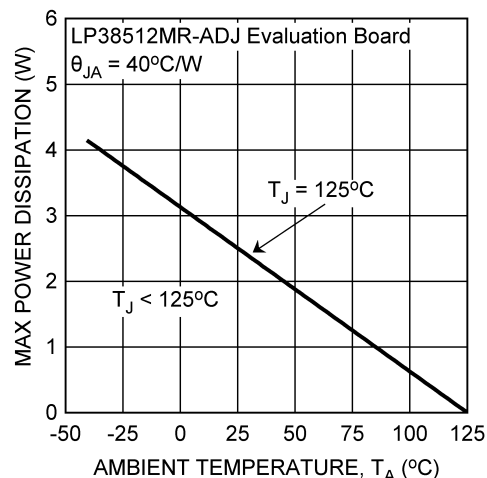


Figure 5. Maximum Power Dissipation vs Ambient Temperature

8 Pin Out

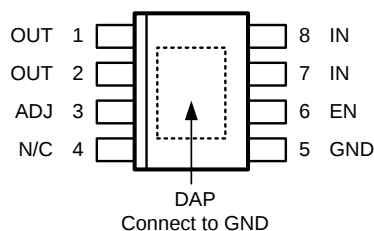


Figure 6. Pin Out

9 Schematic Diagram

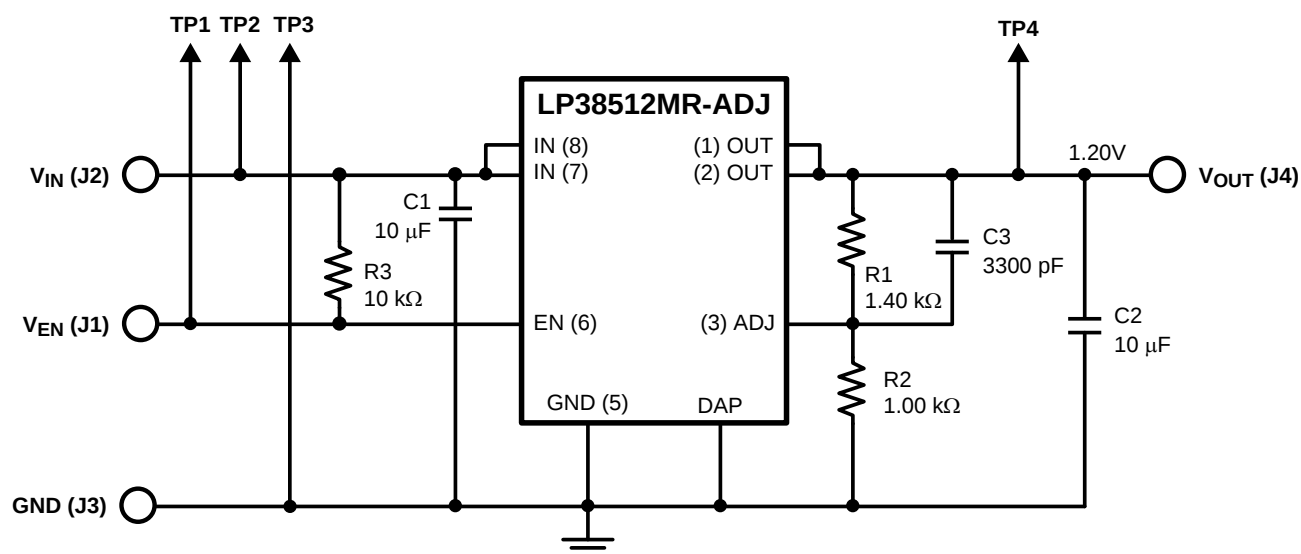


Figure 7. Evaluation Board Schematic.

10 Bill of Materials

Table 2. Bill of Materials

ID	Name	Description	Manufacturer	Part Number
PCB	PCB	Printed Circuit Board	Texas Instruments	600174
U1	U1	LP38512	Texas Instruments	LP38512
C1	C _{IN}	Capacitor: 10 μ F; $\pm$ 10%; MLCC; 10V; X7R; 1210	AVX	1210ZC106KAT2A
C2	C _{OUT}	Capacitor: 10 μ F; $\pm$ 10%; MLCC; 10V; X7R; 1210		1210ZC106KAT2A
C3	C _{FF}	Capacitor: 3300 pF; $\pm$ 10%; MLCC; 50V; X7R; 0805	KEMET	C0805C332K5RAC
J1	V _{EN}	Banana Jack : Insulated Solder Terminal; White	Johnson Components	108-0901-001
J2	V _{IN}	Banana Jack : Insulated Solder Terminal; Red		108-0902-001
J3	GND	Banana Jack : Insulated Solder Terminal; Black		108-0903-001
J4	V _{OUT}	Banana Jack : Insulated Solder Terminal; Orange		108-0906-001
R1	R1	Resistor: 1.40 k Ω , $\pm$ 1%; Thick Film; 125 mW; $\pm$ 100 ppm; 0805	VISHAY DALE	CRCW08051K40FK
R2	R2	Resistor: 1.00 k Ω , $\pm$ 1%; Thick Film; 125 mW; $\pm$ 100 ppm; 0805		CRCW08051K00FK
R3	R3	Resistor: 10.0 k Ω , $\pm$ 1%; Thick Film; 125 mW; $\pm$ 100 ppm; 0805		CRCW080510K0FK
TP1	TP _{EN}	Turret Terminal : Mounting Hole Diameter = 0.062"	Keystone	1593–2
TP2	TP _{IN}			
TP3	TP _{GND}			
TP4	TP _{OUT}			

11 PCB Layout

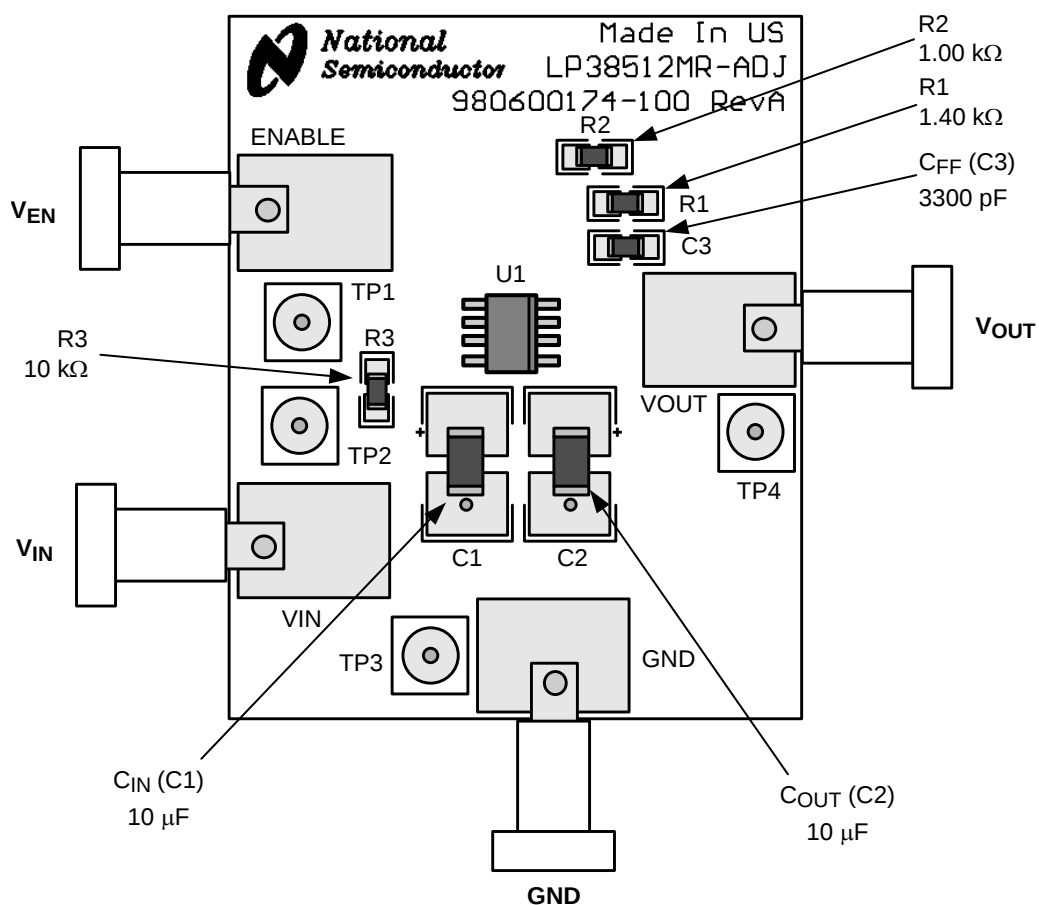


Figure 8. Evaluation Board Component and Pin Layout

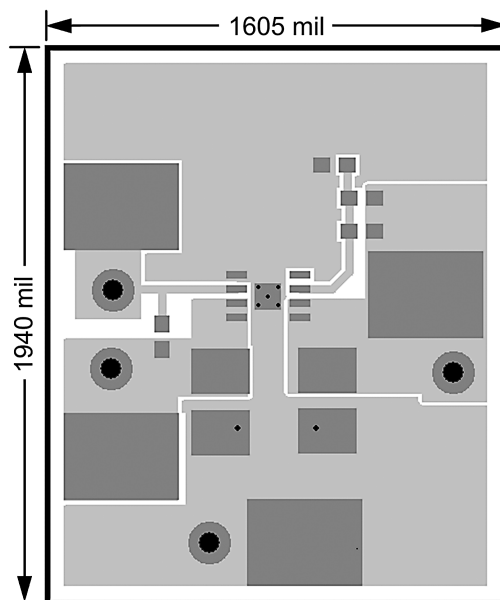


Figure 9. Top Side Copper Area

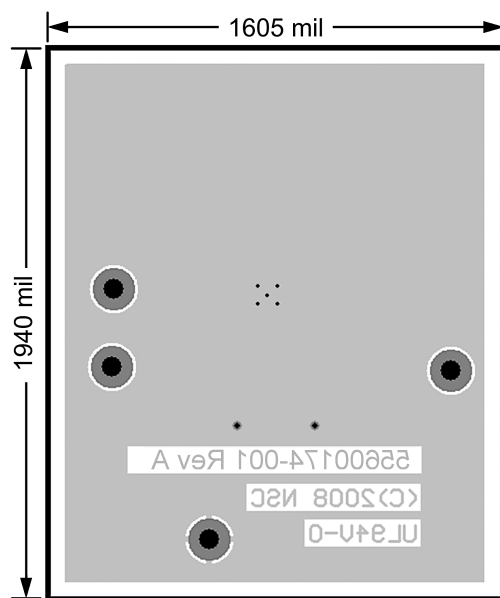


Figure 10. Bottom Side Copper Area

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